PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
JIAN GAO	06/12/2016
HONGPO GAO	06/12/2016
JAMIN JIANBIN KANG	06/12/2016
GENG HAN	06/12/2016
XINLEI XU	06/12/2016

RECEIVING PARTY DATA

Name:	EMC CORPORATION
Street Address:	176 SOUTH STREET
City:	HOPKINTON
State/Country:	MASSACHUSETTS
Postal Code:	01748

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16528286

CORRESPONDENCE DATA

Fax Number: (508)366-4688

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 508-616-2900
Email: Docket@BainwoodHuang.com
Correspondent Name: BAINWOOD, HUANG & ASSOCIATES, LLC
Address Line 1: 2 CONNECTOR ROAD
Address Line 4: WESTBOROUGH, MASSACHUSETTS 01581

ATTORNEY DOCKET NUMBER:	1003-752.001
NAME OF SUBMITTER:	DAVID E. HUANG, ESQ.
SIGNATURE:	/David E. Huang, Reg. No. 39,229/
DATE SIGNED:	08/26/2019

Total Attachments: 7
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ASSIGNMENT

WHEREAS, we, Jian Gao, Hongpo Gao, Jamin Jianbin Kang, Geng Han and Xinlei Xu have invented an invention comprising and/or embodying certain improvements or discoveries or both as described in an application for Letters Patent of the United States entitled *MANAGING STORAGE ARRAY CONFIGURATION* (Application), the specification of which:

☐ is being executed on even date herewith and is about to be filed in the United States Patent Office;

☒ was filed on 7/31/2019 as U.S. Application No. 16/528,286;

☐ was patented under U.S. Patent No. __________ on __________.

WHEREAS, EMC Corporation (hereinafter "ASSIGNEE"), a corporation organized and existing under the laws of the Commonwealth of Massachusetts and having a usual place of business at 176 South Street, Hopkinton, Massachusetts 01748 desires to acquire an interest therein in accordance with agreements duly entered into with us;

NOW, THEREFORE, to all whom it may concern be it known that for and in consideration of said agreements and of other good and valuable consideration, the receipt of which is hereby acknowledged, we have sold, assigned and transferred and by these presents do hereby sell, assign and transfer unto said ASSIGNEE, its successors, assigns and legal representatives, the entire right, title and interest in and throughout the United States of America, its territories and all foreign countries, in and to said invention as described in said application, together with the entire right, title and interest in and to said application and such Letters Patent as may issue thereon; said invention, application and Letters Patent to be held and enjoyed by said ASSIGNEE for its own use and behalf and for its successors, assigns and legal representatives, to the full end of the term for which said Letters Patent may be granted as fully and entirely as the same would have been held by us had this assignment and sale not been made; we hereby convey to ASSIGNEE all rights arising under or pursuant to any and all international agreements, treaties or laws relating to the protection of industrial property by filing any such applications for Letters Patent. We hereby acknowledge that this assignment, being of the entire right, title and interest in and to said invention, carries with it the right in ASSIGNEE to apply for and obtain from competent authorities in all countries of the world any and all Letters Patent by attorneys and agents of ASSIGNEE's selection and the right to procure the grant of all such Letters Patent to ASSIGNEE for its own name as assignee of the entire right, title and interest therein;

AND, we hereby further agree for ourselves and our executors and administrators to execute upon request any other lawful documents and likewise to perform any other lawful acts which may be deemed necessary to secure fully the aforesaid invention to said ASSIGNEE, its successors, assigns and legal representatives, but at its or their expense and charges, including the execution of applications for patents in foreign countries, and the execution of substitution, reissue, divisional or continuation applications and preliminary or other statements and the giving of testimony in any interference or other proceeding in which said invention or any application or patent directed thereto may be involved;

AND, we do hereby authorize and request the Commissioner of Patents of the United States to issue such Letters Patent as shall be granted upon said application or applications based thereon to said ASSIGNEE, its successors, assigns, and legal representatives;

AND, we hereby authorize our attorneys, EMC Corporation, to insert here in parenthesis (16/528,286 filed 7/31/2019) the application number and filing date of said Application (or foreign counterpart application) to facilitate the recording or other official processing of this Assignment.

IN TESTIMONY WHEREOF, we have hereunto set our hands and affixed our seals as set forth below:

Date: 2016.6.12

Inventor's Signature

Print full name of inventor	Jian Gao
Residence	8th Floor, Building #D, Tsinghua Science Park Zhongguancun Dong Road 1#, Haidian District Beijing, CN
Citizenship	CN
Mailing Address	Same as above

I, Xiongcheng Li (name of first witness), whose residential address is
7/F Block D. Tsinghua science Park, No.1 Zhongguancun East Road, Haidian District Beijing
was personally present and did see Jian Gao (name of person signing the assignment), who is personally known to me, execute the above assignment.

Xiongcheng Li (signature of first witness)
Signed at Tsinghua Science Park (location of witness signature)
on this day, Jun. 12, 2016 (date of signature).

I, Jibing . Dong (name of second witness), whose residential address is
7F Block D. Tsinghua Science Park NO.1 zhongguancun East Road, Haidian. District . BJ
was personally present and did see Jian Gao (name of person signing the assignment), who is personally known to me, execute the above assignment.

Jibing . Dong (signature of second witness)
Signed at Tsinghua Science Park (location of witness signature)
on this day, Jun 12. , 2016 (date of signature).

Date: 2016.6.12

Hongpo Gao
Inventor's Signature

Print full name of inventor Hongpo Gao

Residence TSP 7FL, Zhongguancun East Road 1
Beijing, CN

Citizenship CN

Mailing Address Same as above

I, Xiongcheng Li (name of first witness), whose residential address is
7/F Block D. Tsinghua Science Park, No.1 Zhongguancun East Road, Haidian District Beijing
was personally present and did see Hongpo Gao (name of person signing the assignment), who is personally known to me, execute the above assignment.

Xiongcheng Li (signature of first witness)
Signed at Tsinghua Science Park (location of witness signature)
on this day, Jun. 12, 2016 (date of signature).

I, Jibing Dong (name of second witness), whose residential address is
7/F. Block D. Tsinghua Science Park. No.1 Zhongguancun East Road. HaiDian District. BJ
was personally present and did see Hongpo Gao (name of person signing the assignment), who is personally known to me, execute the above assignment.

Jibing. Dong (signature of second witness)
Signed at Tsinghua Science Park. (location of witness signature)
on this day, Jun. 12, 2016. (date of signature).

Date: 2016.6.12 康剑斌

Inventor's Signature

Print full name of inventor Jamin Jianbin Kang

Residence 13#902 WenhuiYuan, Haidian
Beijing, CN

Citizenship CN

Mailing Address Same as above

I, Xiongcheng Li (name of first witness), whose residential address is 7/F Block D, Tsinghua Science Park, No. 1, Zhongguancun East Road, Haidian District Beijing was personally present and did see Jamin Jianbin Kang (name of person signing the assignment), who is personally known to me, execute the above assignment.

Xiongcheng Li (signature of first witness)

Signed at Tsinghua Science Park (location of witness signature)

on this day, Jun 12, 2016 (date of signature).

I, Jibing . Peng (name of second witness), whose residential address is 7/F Block D . Tsinghua Science Park . No. 1 . Zhongguancun East Road, Haidian District BJ was personally present and did see Jamin Jianbin Kang (name of person signing the assignment), who is personally known to me, execute the above assignment.

Jibing . Peng (signature of second witness)

Signed at Tsing Hua Science Park (location of witness signature)

on this day, Jun 12, 2016 (date of signature).

Date: 2016.06.12

Geng. Han
Inventor's Signature

Print full name of inventor	Geng Han
Residence	12-5-502, Xinlongcheng, Changping Beijing, CN
Citizenship	CN
Mailing Address	Same as above

I, Xiongcheng Li (name of first witness), whose residential address is 7/F Block D. Tsinghua Science Park, No.1 Zhongguancun East Road, Haidian District Beijing was personally present and did see Geng Han (name of person signing the assignment), who is personally known to me, execute the above assignment.

Xiongcheng Li (signature of first witness)
Signed at Tsinghua Science Park (location of witness signature)
on this day, Jun. 12., 2016 (date of signature).

I, Jibing. Dong (name of second witness), whose residential address is 7/F Block D. Tsinghua Science Park, No. 1. Zhongguancun East Road. Haidian. Distriht. was personally present and did see Geng Han (name of person signing the assignment), who is personally known to me, execute the above assignment.

Jibing. Dong (signature of second witness)
Signed at Tsinghua. Science park. (location of witness signature)
on this day, Jun. 12, 2016 (date of signature).

Date: 2016.6.12.

Xinlei Xu.
Inventor's Signature

Print full name of inventor	Xinlei Xu
Residence	6-6-602, Zhongyuan, Tiantongyuan, Changping Beijing, CN
Citizenship	CN
Mailing Address	Same as above

I, xiongcheng Li (name of first witness), whose residential address is 7/F. Block D. TsingHua Science Park, No. 1, Zhongguancun East Road, Haidian District Beijing was personally present and did see Xinlei Xu (name of person signing the assignment), who is personally known to me, execute the above assignment.

xiongcheng Li (signature of first witness)
Signed at Tsinghua Science Park (location of witness signature)
on this day, Jun. 12 xiongcheng Li, 2016 (date of signature).

I, Jibing Dong (name of second witness), whose residential address is 7F Block D. TsingHua. Science Park. No. 1. zhongguancun. East Road, Haidian. District. BJ was personally present and did see Xinlei Xu (name of person signing the assignment), who is personally known to me, execute the above assignment.

Jibing Dong (signature of second witness)
Signed at Tsing Hua Science Park. (location of witness signature)
on this day, Jun 12., 2016 (date of signature).